

This listing of claims will replace all prior versions of claims in the application.

Claim 1 (original): A positive-acting photoimageable composition comprising a photoactive component and a polymer component,
the polymer component comprising a polymer that comprises Si atoms and silanol groups,
wherein the polymer has a ratio of silanol groups to Si atoms of about 0.01 to 1.5.

Claims 2-4 (cancelled)

Claim 5 (original): The photoimageable composition of claim 1 wherein the ratio of silanol groups to Si atoms is about 0.01 to 0.4.

Claims 6-8 (cancelled).

Claim 9 (previously presented): The photoimageable composition of claim 1 wherein the polymer comprises aqueous base-solubilizing groups.

Claim 10 (previously presented): The photoimageable composition of claim 9 wherein the aqueous base-solubilizing groups are fluorinated alcohols, sulfonamide, carboxylic acid and/or thiols.

Claim 11 (cancelled).

Claim 12 (previously presented): The photoimageable composition of claim 9 wherein the polymer contains at least about 20 mole percent of aqueous base-solubilizing groups based on total units of the polymer.

Claims 13-14 (cancelled).

Claim 15 (previously presented): The photoimageable composition of claim 9 wherein the polymer contains at least about 50 mole percent of aqueous base-solubilizing groups based on total units of the polymer.

Claim 16 (previously presented): The photoimageable composition of claim 1 wherein the polymer comprises units that are free of photoacid-labile groups and aqueous base-solubilizing groups.

Claim 17 (previously presented): The photoimageable composition of claim 1 wherein the polymer comprises at least two distinct repeat units.

Claims 18-19 (cancelled).

Claim 20 (previously presented): The photoimageable composition of claim 1 wherein the polymer comprises at least three distinct repeat units of: 1) units that contain photoacid-labile groups; 2) units that are free of photoacid-labile and aqueous base-solubilizing groups; and 3) units that comprise an aqueous base-solubilizing group.

Claim 21 (previously presented): The photoimageable composition of claim 1 wherein the composition is a chemically-amplified positive acting photoresist.

Claim 22 (original): The photoimageable composition of claim 1 wherein the composition is a negative-acting photoresist.

Claims 23-29 (cancelled).

Claim 30 (previously presented): A coated substrate comprising:

- a) a polymer composition coating layer applied over a substrate surface;
- b) a coating layer of a photoimageable composition of claim 1 disposed over the polymer composition coating layer.

Claims 31-36 (cancelled):

Claim 37 (previously presented): A coated substrate of claim 30 wherein the polymer composition does not contain a polymer with Si groups.

Claim 38 (previously presented): A coated substrate of claim 30 wherein the polymer composition is not photoimageable.

Claim 39 (previously presented): A method for forming a electronic device, comprising:

- (a) applying on a substrate a coating layer of a polymer composition;
- (b) over the polymer composition coating layer, applying a photoimageable composition of claim 1;
- (c) exposing the photoimageable composition coating layer to activating radiation and developing the exposed photoimageable layer.

Claim 40 (original): The method of claim 39 wherein a coating layer of the photoimageable composition coating layer is exposed with radiation having a wavelength of about 248 nm.

Claim 41 (original): The method of claim 39 wherein a coating layer of the photoimageable composition coating layer is exposed with radiation having a wavelength of less than about 200 nm.

Claim 42 (original): The method of claim 39 wherein a coating layer of the photoimageable composition coating layer is exposed with radiation having a wavelength of about 193 nm or 157 nm.

Claims 43-59 (cancelled).

Claim 60 (new): The method of claim 39 wherein the substrate is a silicon wafer.